

IN THE CLAIMS

1. (Currently Amended) A method for aligning at least one optic and/or electronic component (2) on a substrate (3) or a corresponding support structure, characterised in that the method comprises:
 - arranging a hole (4) in the support structure;
 - arranging at least three stud bumps (5) on the surface of the component (2);
 - and
 - arranging said stud bumps along the periphery of the hole (4) for alignment of the component (2) to the hole (4).

2. (Currently Amended) A method according to claim 1, characterised in that aligning the component (2) is performed by arranging the outer surfaces of the stud bumps against the hole walls.

3. (Currently Amended) A method for aligning at least one optic fibre (1) and an optoelectronic component (2) to each other according to claim 1, wherein the component (2) is mounted on a supporting structure (3) and the optic fibre (1) is connected to the optoelectronic component (2),
 - characterised in that the method comprises:
 - threading the optic fibre (1) through the hole, and
 - aligning the optic fibre (1) and the component (2) with each other by means of the stud bumps (5).

4. (Currently Amended) A method according to claims 1 or 3; characterised in

that aligning the fibre is performed by arranging the fibre against the inner surfaces of the stud bumps.

5. (Currently Amended) A method according to claims 1 to 4, characterised in that the stud bumps have at least partly a conical and/or rounded surfaces, and that aligning the optic fibre (1) with the component is performed by adapting the optic fibre along sloping conical inner surfaces and a horizontal brim in the stud bumps.

6. (Currently Amended) A method according to claim 1 or 4, characterised in that the component is a surface emitting optoelectronic component, that the optic fibre is arranged perpendicular to the support structure, and that the fibre is connected to a radiating source on the metallized surface (22) of the component facing the substrate.

7. (Currently Amended) A method according to claim 1, characterised in that a conductive adhesive (7a) is used on the stud bump (5) outer surfaces to accomplish an electrical connection to the support structure (3).

8. (Currently Amended) A method according to claim 1, characterised in that a direct bonding method is used to connect the stud bumps (5) to the support structure (3).

9. (Currently Amended) A method according to claim 1, characterised in that the stud bumps are of a solder material, and that a solder connection is used to connect the stud bumps ~~(5)~~ to the support structure ~~(3)~~.

10. (Currently Amended) An arrangement for aligning at least one optic and/or electronic component ~~(2)~~ on a substrate ~~(3)~~ or a corresponding support structure, characterised in that the arrangement comprises:

a hole ~~(4)~~ in the support structure;

at least three stud bumps ~~(5)~~ arranged on the surface of the component ~~(2)~~ along the periphery of the hole ~~(4)~~, for aligning the component ~~(2)~~ centered to the hole ~~(4)~~.

11. (Currently Amended) A arrangement according to claim 10, characterised in that the stud bumps have at least partly a conical and/or rounded surfaces, and that an optic fibre ~~(1)~~ is aligned with the component by adapting the optic fibre along sloping conical inner surfaces and against a horizontal brim in the stud bumps.

12. (Currently Amended) An arrangement according to claim 10 ~~or 11~~, characterised in that the component is a surface emitting optoelectronic component, that the optic fibre is arranged perpendicular to the substrate, and that the fibre is connected to a radiating source on the metallized surface ~~(22)~~ of the component facing the substrate.

13. (Currently Amended) An arrangement according to claim 10, characterised in that a conductive adhesive ~~(7a)~~ is used on the stud bump ~~(5)~~ outer surfaces to accomplish an electrical connection to the substrate ~~(3)~~.
14. (Currently Amended) An arrangement according to claim 10, characterised in that direct bonding is used to connect the stud bumps ~~(5)~~ to the substrate ~~(3)~~.
15. (Currently Amended) An arrangement according to claim 10, characterised in that the stud bumps are of a solder material, and that a solder connection is used to connect the stud bumps ~~(5)~~ to the substrate ~~(3)~~.
16. (Currently Amended) An arrangement according to claim 10, characterised in that the substrate ~~(3)~~ consists of at least two layers ~~(31-33)~~, and that the diameter of the hole ~~(4)~~ portion(s) ~~(41)~~ in the layer(s) ~~(31)~~ near the component is bigger having place for both the stud bumps and the optic fibre than in other opening portion(s) ~~(42)~~ having a diameter essentially corresponding the diameter of the optic fibre.